

HSM2694

Silicon Epitaxial Planar Diode for Tuner Band Switch

REJ03G0110-0200Z

(Previous: ADE-208-095A)

Rev.2.00

Oct.08.2003

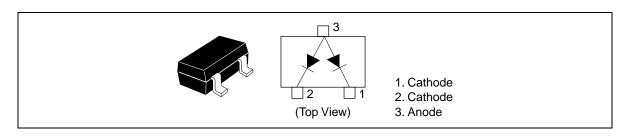
Features

- Low forward resistance. $(r_f = 0.9 \Omega \text{ max})$
- Low capacitance. (C = 1.2 pF max)
- MPAK package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Code
HSM2694	В3	MPAK

Pin Arrangement



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Reverse voltage	V_{R}	35	V
Power dissipation	Pd *1	150	mW
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-45 to +125	°C
Operation temperature	Topr	-20 to +60	°C

Note: 1. Two device total

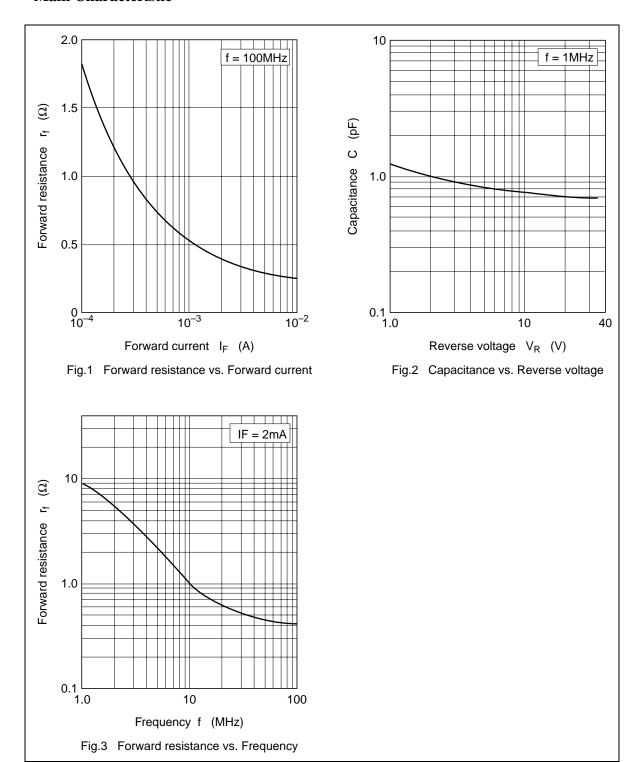
Electrical Characteristics *1

 $(Ta = 25^{\circ}C)$

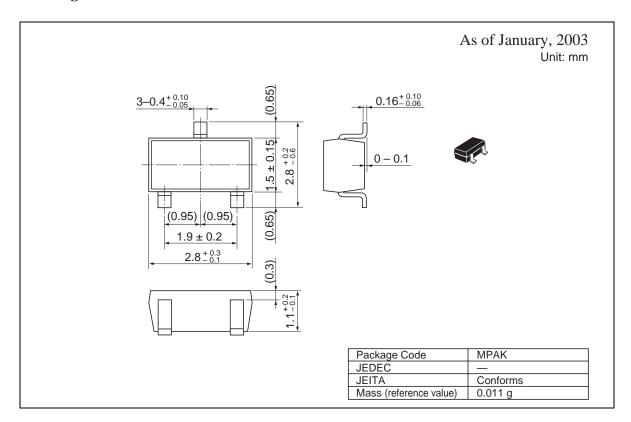
Item	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse voltage	V_R	35	_	_	V	I _R = 10 μA
Reverse current	I _R	_	_	50	nA	V _R = 25 V
Forward voltage	V _F	_	_	1.0	V	I _F = 10 mA
Capacitance	С	_	_	1.2	рF	$V_R = 6 \text{ V}, f = 1 \text{ MHz}$
Forward resistance	r,	_	_	0.9	Ω	I _F = 2 mA, f = 100 MHz

Note: 1. Per one device

Main Characteristic



Package Dimensions



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